

ABSTRACT OF THE DISCLOSURE

POLISHING APPARATUS

The polishing apparatus has: a polishing pad that has a polishing surface to polish a semiconductor wafer; a polishing table to which a back surface of the polishing pad on an opposite side of the polishing surface can be attached; a top ring that is opposed to the polishing surface, and can hold the semiconductor wafer; and an eddy current sensor that is arranged in the polishing table, and detects an end point of polishing. The polishing table has on an attachment surface a projection member projecting from the attachment surface to which the polishing pad is attached. The back surface of the polishing pad has a concave portion in a portion opposed to the projection member, and at least a part of the eddy current sensor is arranged inside the projection member.

Selected Drawings: FIG. 1